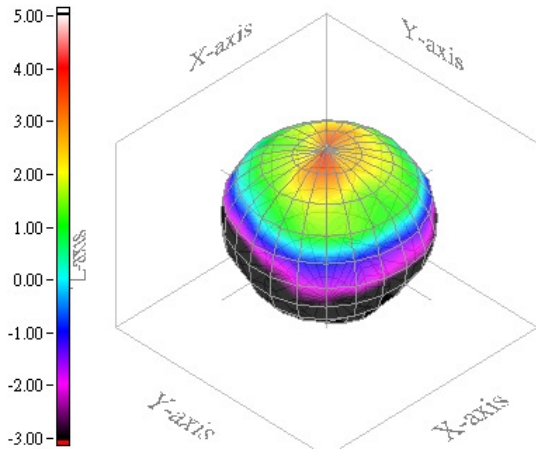
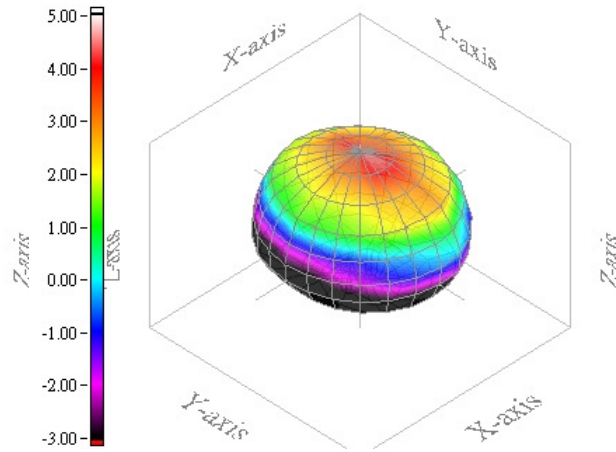


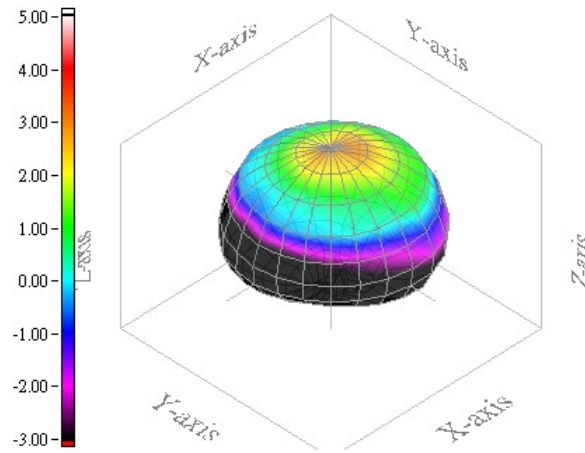
2.2 Gain Pattern (Unit : dBic)



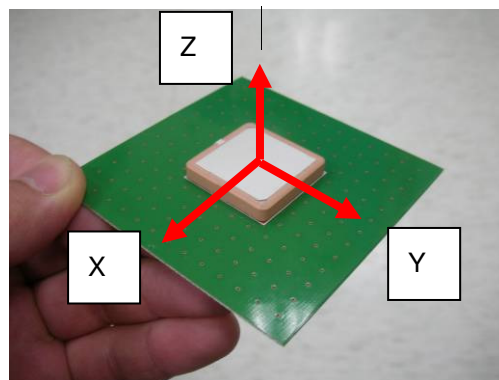
1575.42 MHz



1593 MHz



1610 MHz



UNLESS OTHER SPECIFIED TOLERANCES ON :	
X=±	X.X=±
ANGLES=±	X.XX=±
	HOLEDIA=±
SCALE :	UNIT : mm
DRAWN BY:詹雅萍	CHECKED BY:馬敏勝
DESIGNED BY:鄭大福	APPROVED BY:曾源標
TITLE : PA1590MI4G-101-SMD Engineering Specification	

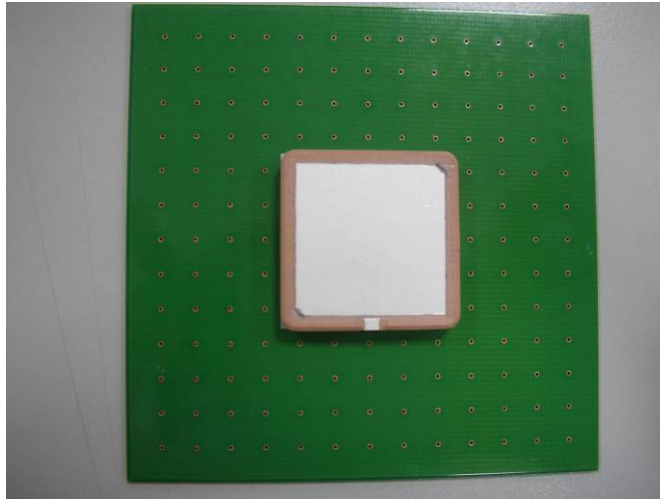


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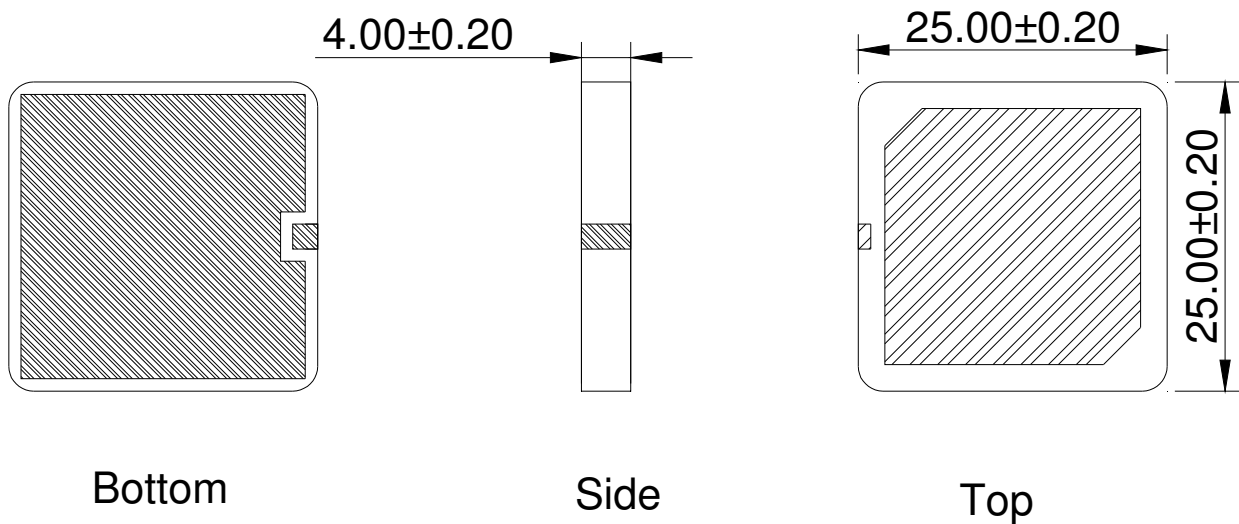
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2.3 Antenna Direction



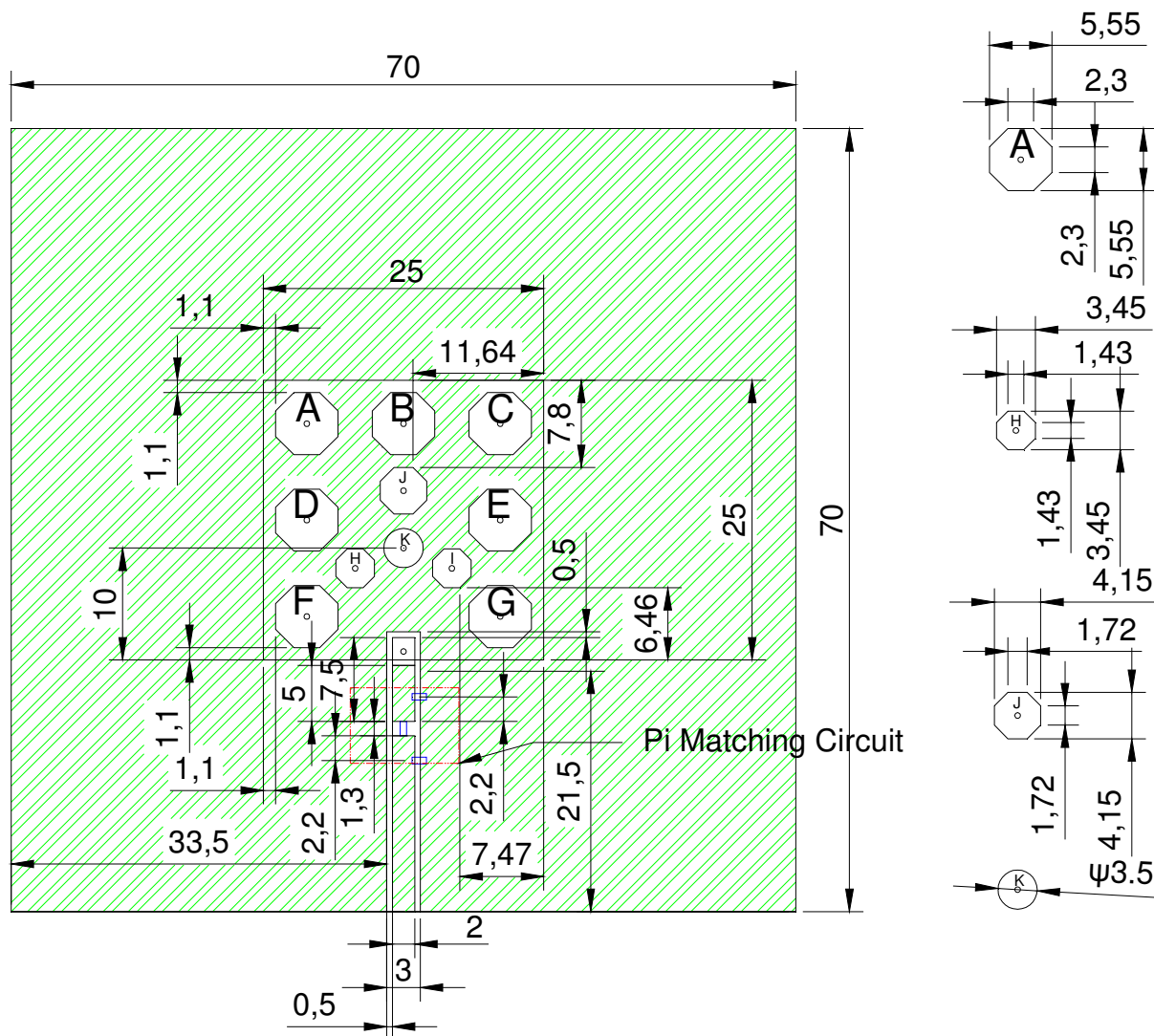
3. Dimension



unit : mm

UNLESS OTHER SPECIFIED TOLERANCES ON :		 INPAQ TECHNOLOGY CO., LTD.	
X=±	X.X=±		
ANGLES=±	HOLEDIA=±		
SCALE :	UNIT : mm	THIS DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF INPAQ TECHNOLOGY CO.,LTD.AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR DEVICES WITHOUT PERMISSION	
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4. Test Condition Ground Plane (Example for PCB 1 mm)



Top

A.B.C.D.E.F.G. are same soldering pads.

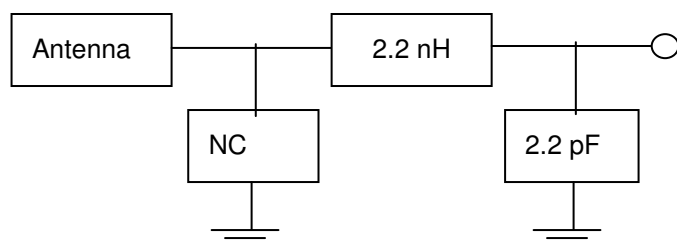
H.I are same soldering pads.

Bottom side needs π matching circuit.

Tolerance: ± 0.2 mm

Unit : mm

π matching circuit:



UNLESS OTHER SPECIFIED TOLERANCES ON :

X=± X.X=± X.XX=±
 ANGLES=± HOLEDIA=±



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SCALE : UNIT : mm

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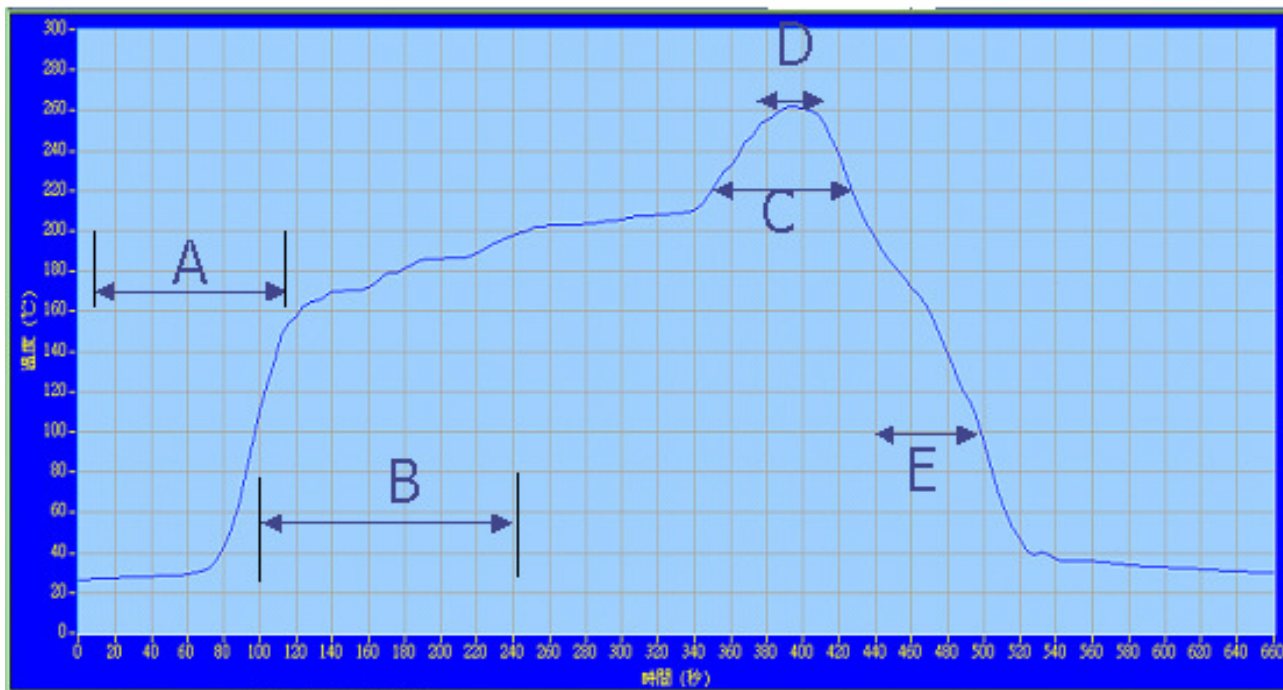
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5. Recommendable Reflow Soldering



A	Rising temperature	The normal to Preheating	60s to 120s
B	Preheating	80°C to 200°C	140s to 150
C	Temperature	220°C to 260°C to 220°C	80 to 90s
D	Main heating	if 260°C	20s~30s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

* The thickness of Solder should be controlled to be higher than 0.1 mm.

UNLESS OTHER SPECIFIED TOLERANCES ON :

X=± X.X=± X.XX=±
 ANGLES=± HOLEDIA=±

SCALE : UNIT : mm

DRAWN BY:詹雅萍 CHECKED BY:馬敏勝

DESIGNED BY:鄭大福 APPROVED BY:曾源標

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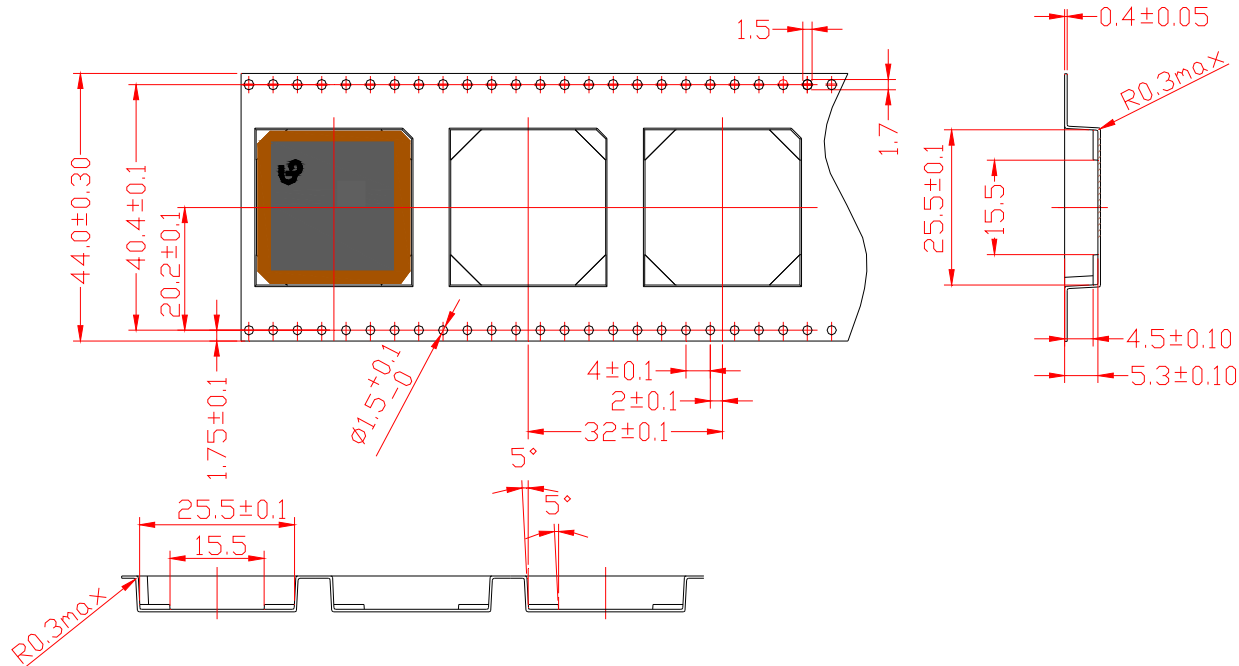


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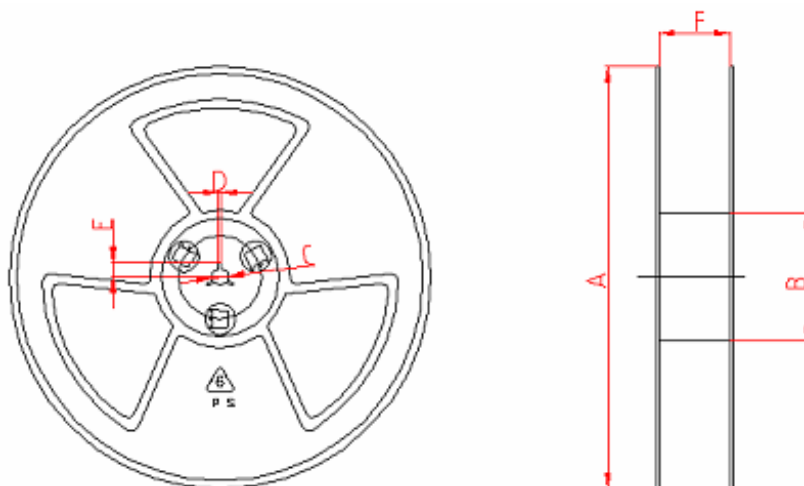
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		P1

6. Delivery mode



7. Taping Reel Dimensions



A	B	C	D	E	F
±2.0	±4.0	±0.2	±0.2	±0.25	±2.0
330	100	13.2	2	10.75	44.4

8. Quantity of Products in the Taping Package

(1) Standard quantity: 200Pcs/Reel

UNLESS OTHER SPECIFIED TOLERANCES ON :

X=± X.X=± X.XX=±
 ANGLES=± HOLEDIA=±



INPAQ TECHNOLOGY CO., LTD.

SCALE : UNIT : mm

DRAWN BY: 詹雅萍 CHECKED BY: 馬敏勝

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